

EPO-TEK® 377

For Reference Only
High Temperature Epoxy

Date: September 2017 Recommended Cure: 150°C / 1 Hour

Rev: VIII
No. of Components: Two
Mix Ratio by Weight: 1:1

Specific Gravity: Part A: 1.15 Part B: 1.22

Pot Life: 24 Hours

Shelf Life- Bulk: One year at room temperature

NOTES:

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

<u>Product Description:</u> EPO-TEK® 377 is a two component, high Tg, fiber optic grade epoxy. It is well suited for semiconductor, medical and optical applications.

<u>Typical Properties:</u> Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Clear/Colo	rless Part B: Amber
* Consistency:	Pourable liquid	
* Viscosity (23°C) @ 100 rpm:	150 - 300	cPs
Thixotropic Index:	N/A	
* Glass Transition Temp:	≥ 95	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	57	x 10 ⁻⁶ in/in°C
Above Tg:	210	x 10 ⁻⁶ in/in°C
Shore D Hardness:	67	
Lap Shear @ 23°C:	1,456	psi
Die Shear @ 23°C:	≥ 10	Kg 3,556 psi
Degradation Temp:	375	°C
Weight Loss:		
@ 200°C:	0.06	%
@ 250°C:	0.17	%
@ 300°C:	0.50	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	373,622	psi
Ion Content:	Cl ⁻ : 26 ppm	Na ⁺ : 15 ppm
	NH ₄ +: 22 ppm	K+: 3 ppm
* Particle Size:	N/A	

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	N/A	
Volume Resistivity @ 23°C:	$\geq 1 \times 10^{13}$	Ohm-cm
Dielectric Constant (1KHz):	3.36	
Dissipation Factor (1KHz):	0.005	

OPTICAL PROPERTIES @ 23°C		
Spectral Transmission:	≥ 90% @ 600-1000	nm
	≥ 98% @ 1000-6800	nm
Refractive Index:	1.5195 @ 589	nm



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EPO-TEK® 377 Advantages & Suggested Application Notes:

- Low viscosity epoxy with excellent handling characteristics. It can be used for encapsulating or potting. It may be applied by hand, pouring, spin coating, brushing, dipping, or automated dispensers.
- NASA approved, low outgassing epoxy http://outgassing.nasa.gov/
- Suggested Semiconductor Grade epoxy:
 - Spin coating at wafer level for MEMS fabrication of pressure sensors and accelerometers.
 - Wafer-to-wafer bonding in CSP.
 - o Capillary underfill of flip chip packaged die.
- Suggested Optical grade epoxy, opto-electronic packaging:
 - Transmission in NIR from 700 900 nm >95%.
 - Glass seal, hermetic seal of glass plates in LCD fabrication.
 - Hermetic seal of IR-filter window to aluminum cap of TO-Can in hybrid packaged IR sensors.
- Suggested Industrial: resist salt water, hydraulic fluids, motor oil, alcohol, 10% nitric acid, 10% sulfuric acid, 10% ammonia solution and most solvents.